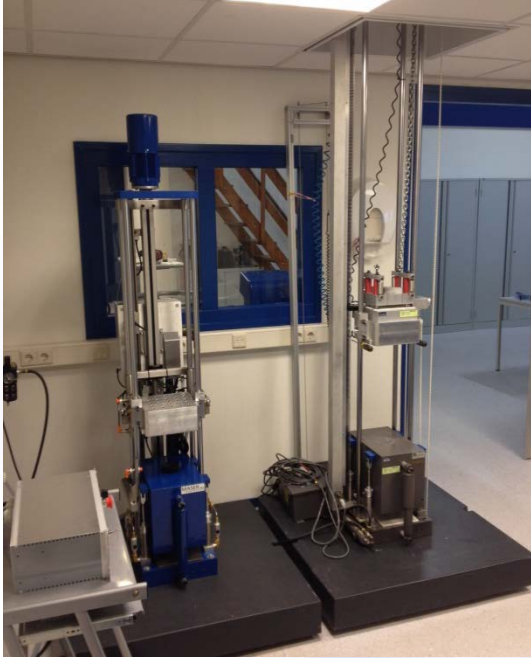


Hermetic package test service



HERMETIC PACKAGE TESTS:

- Tests for open cavity packages (ceramic) and/or MEMS devices
- Mechanical shock
- Vibration Variable Frequency
- Constant Acceleration
- Gross/Fine leak
- Package drop
- According to JESD47
- AEC-Q100 TEST GROUP G



MECHANICAL SHOCK:

- 5 shocks pulses Y1 only
- 0,5ms duration
- 1500g peak acceleration
- JESD22-B104
- MIL-STD-883 method 2002



VIBRATION VARIABLE FREQUENCY:

- 20Hz to 2kHz in > 4min
- 4x in each direction
- 50g peak acceleration
- JESD22-B103
- MIL-STD-883 method 2007

Hermetic package test service



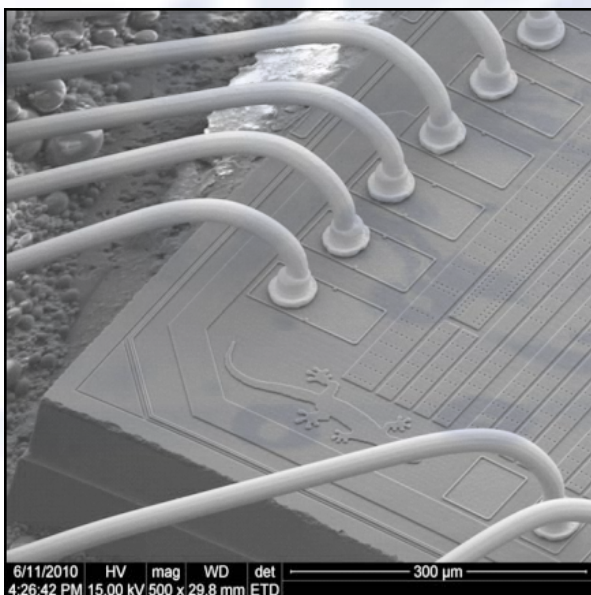
CONSTANT ACCELERATION:

- 30 kg force < 40 pin packages
- 20 kg force for \geq 40 pin packages
- Y1 plane only
- MIL-STD-883 method 2001



GROSS/FINE LEAK:

- Pressurize sample with He
- Helium leak tester
- Pressurize sample with special low boiling point fluid
- Bubble tester
- JESD22-A109
- MIL-STD-883 method 1014



OTHER HERMETIC PACKAGE QUALIFICATION TESTS:

- Temperature Cycling (TC)
- Bond Pull Strength (BPS)
- Bond Ball Shear (WBS)
- Die Shear (DS)
- Solderability (SOLD)
- Solder Ball Shear (SBS)
- External Visual
- Physical Dimensions (PD)
- Lead integrity (LI)
- Lid Torque
- Particle Impact Noise Detection (PIND)
- Residual Gas Analysis (RGA)
- Tin Whisker Acceptance